Technique for the Nitride Growth of Semipolar Thin Films, Heterostructures, and Semiconductor Devices
Tech ID: 25247 / UC Case 2005-668-0

BRIEF DESCRIPTION
A method to grow semipolar (Ga, Al, In, B)N thin films, heterostructures, and devices on suitable substrates or planar templates in which a large area of the semipolar film is parallel to the substrate surface.

BACKGROUND
The usefulness of gallium nitride (GaN) and its ternary and quaternary compounds incorporating aluminum and indium has been well established for fabrication of visible and ultraviolet optoelectronic devices. Current nitride technology for these devices uses nitride films grown along the polar c-direction; however, quantum-well active regions in devices suffer from the quantum-confined Stark effect (QCSE). One way to combat the issue is to grow films on semipolar planes of GaN in order to improve device performance by reduce polarization effects and increasing the efficiency of optical transitions.

DESCRIPTION
Researchers at UC Santa Barbara have developed a method to grow semipolar (Ga, Al, In, B)N thin films, heterostructures, and devices on suitable substrates or planar templates in which a large area of the semipolar film is parallel to the substrate surface. The method uses vapor phase epitaxy, such as metalorganic chemical vapor deposition (MOCVD), in order to grow the semipolar structures. Additionally, this technique alters the crystal growth orientation in order to reduce polarization effects in nitride thin films. This method is stable, energy efficient and cost-effective.

ADVANTAGES
▶ Reduces the negative impact of polarization
▶ Improved device efficiency
▶ Improved crystal growth orientation

APPLICATIONS
▶ LEDs and Laser Diodes (LDs)
▶ Semiconductors

PATENT STATUS
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OTHER INFORMATION
KEYWORDS
indssl, indled, MOCVD, thin films

CATEGORIZED AS
▶ Optics and Photonics
▶ All Optics and Photonics
▶ Energy
▶ Lighting
▶ Semiconductors
▶ Design and Fabrication

RELATED CASES
2005-668-0

ADDITIONAL TECHNOLOGIES BY THESE INVENTORS
▶ Method for Improved Surface of (Ga,Al,In,B)N Films on Nonpolar or Semipolar Substrates
▶ High Efficiency LED with Optimized Photonic Crystal Extractor
▶ Enhanced Optical Polarization of Nitride LEDs by Increased Indium Incorporation
▶ Etching Technique for the Fabrication of Thin (Al, In, Ga)N Layers
▶ Lateral Growth Method for Defect Reduction of Semipolar Nitride Films
Flexible Arrays of MicroLEDs using the Photoelectrochemical (PEC) Liftoff Technique
Vertical Cavity Surface-Emitting Lasers with Continuous Wave Operation
Achieving “Active P-Type Layer/Layers” In III-Nitride Epitaxial Or Device Structures Having Buried P-Type Layers
High-Quality N-Face GaN, InN, AlN by MOCVD
Low-Cost Zinc Oxide for High-Power-Output, GaN-Based LEDs (UC Case 2010-183)
Internal Heating for Ammonothermal Growth of Group-III Nitride Crystals
Defect Reduction in GaN films using in-situ SiNx Nanomask
Enhanced Light Extraction LED with a Tunnel Junction Contact Wafer Bonded to a Conductive Oxide
Highly Efficient Blue-Violet III-Nitride Semipolar Laser Diodes
Hybrid Growth Method for Improved III-Nitride Tunnel Junction Devices
Phosphor-Free White Light Source
Volumetric Hole Injection with Intentional V-Defects
Control of Photoelectrochemical (PEC) Etching by Modification of the Local Electrochemical Potential of the Semiconductor Structure
Low Temperature Deposition of Magnesium Doped Nitride Films
Device Structures Utilizing Barrier Enhancement Conductive Materials on N-polar III-N
Transparent Mirrorless (TML) LEDs
Improved GaN Substrates Prepared with Ammonothermal Growth
Laser Diode With Tunnel Junction Contact Surface Grating
Optimization of Laser Bar Orientation for Nonpolar Laser Diodes
High Efficiency Semipolar AlGaN-Cladding-Free Laser Diodes
High Mobility Group-III Nitride Transistors with Strained Channels
Method for Growing Self-Assembled Quantum Dot Lattices
A Structure For Increasing Mobility In A High-Electron-Mobility Transistor
Method for Enhancing Growth of Semipolar Nitride Devices
III-Nitride Tunnel Junction with Modified Interface
Growth of Polyhedron-Shaped Gallium Nitride Bulk Crystals
Nonpolar III-Nitride LEDs With Long Wavelength Emission
Fabrication of Relaxed Semiconductor Films without Crystal Defects
Improved Fabrication of Nonpolar InGaN Thin Films, Heterostructures, and Devices
Growth of High-Quality, Thick, Non-Polar M-Plane GaN Films
Methods for Locally Changing the Electric Field Distribution in Electron Devices
Increased Light Extraction with Multistep Deposition of ZnO on GaN
Method for Manufacturing Improved III-Nitride LEDs and Laser Diodes: Monolithic Integration of Optically Pumped and Electrically Injected III-Nitride LEDs
Selective-Area Mesoporous Semiconductors And Devices For Optoelectronic And Photonic Applications
High-Efficiency, Mirrorless Non-Polar and Semi-Polar Light Emitting Devices
Method for Growing High-Quality Group III-Nitride Crystals
Incorporating Temperature-Sensitive Layers in III-N Devices
Controlling Linearity in N-Polar GaN MISHEMTs
Oxyfluoride Phosphors for Use in White Light LEDs
Enabling Epitaxial Growth On Thin Substrates
(In,Ga,Al)N Optoelectronic Devices with Thicker Active Layers for Improved Performance
MOCVD Growth of Planar Non-Polar M-Plane Gallium Nitride
Reduced Dislocation Density of Non-Polar GaN Grown by Hydride Vapor Phase Epitaxy
N-polar III-N Semiconductor Device Structures Enabled by Wet Chemistry
Heterogeneously Integrated GaN on Si Photonic Integrated Circuits
(AI, In,Ga, B)N Device Structures
Reduction in Leakage Current and Increase in Efficiency of III-Nitride MicroLEDs
GaN-based Vertical Metal Oxide Semiconductor and Junction Field Effect Transistors
Methods for Fabricating III-Nitride Tunnel Junction Devices
3D Hole Injectors for InAlGaN Light-Emitting Diodes
Low-Droop LED Structure on GaN Semi-polar Substrates
Contact Architectures for Tunnel Junction Devices
Semi-polar LED/LD Devices on Relaxed Template with Misfit Dislocation at Hetero-interface
Photoelectrochemical Etching Of P-Type Semiconductor Heterostructures
Semipolar-Based Yellow, Green, Blue LEDs with Improved Performance
Growth of Semipolar III-V Nitride Films with Lower Defect Density
III-Nitride Tunnel Junction LED with High Wall Plug Efficiency

Novel Current-Blocking Layer in High-Power Current Aperture Vertical Electron Transistors (CAVETs)

In-Situ Methods Of Preventing Interfacial Impurities And Dry Etch-Induced Damage In Regrown III-Nitride Structures

Enhanced Hole Injection by P-Type Active Region and Lateral Injection in InAlGaN LEDs

Improved Manufacturing of Solid State Lasers via Patterned of Photonic Crystals

III-N Transistor With Stepped Cap Layers

Solid Solution Phosphors for Use in Solid State White Lighting Applications

Multifaceted III-Nitride Surface-Emitting Laser

Tunable White Light Based on Polarization-Sensitive LEDs

Cleaved Facet Edge-Emitting Laser Diodes Grown on Semipolar GaN

Growth of High-Performance M-plane GaN Optical Devices

Packaging Technique for the Fabrication of Polarized Light Emitting Diodes

Improved Anisotropic Strain Control in Semipolar Nitride Devices

High Light Extraction Efficiency III-Nitride LED

Photoelectrochemical Etching for Chip Shaping Of LEDs

III-V Nitride Device Structures on Patterned Substrates

Hexagonal Wurtzite Type Epitaxial Layer with a Low Alkali-Metal Concentration

Method for Increasing GaN Substrate Area in Nitride Devices

Burying Impurities And Defects In Regrown III-Nitride Structures

Growth of Planar, Non-Polar, A-Plane GaN by Hydride Vapor Phase Epitaxy

Single or Multi-Color High Efficiency LED by Growth Over a Patterned Substrate

GaN-Based Thermoelectric Device for Micro-Power Generation

Polarization-Doped Field Effect Transistors with Increased Performance

Limiting Strain-Relaxation in III-Nitride Heterostructures by Substrate Patterning

Improved Manufacturing of Semiconductor Lasers

LED Device Structures with Minimized Light Re-Absorption

Growth of Planar Semi-Polar Gallium Nitride

Nonpolar (Al, B, In, Ga)N Quantum Well Design

UV Optoelectronic Devices Based on Nonpolar and Semi-polar AlInN and AlInGaN Alloys

Defect Reduction of Non-Polar and Semi-Polar III-Nitrides

III-Nitride Based VCSEL with Curved Mirror on P-Side of the Aperture

Low-Cost Zinc Oxide for High-Power-Output, GaN-Based LEDs (UC Case 2010-150)

Suppression of Defect Formation and Increase in Critical Thickness by Silicon Doping

Wafer Bonding for Embedding Active Regions with Relaxed Nanostructures

Enhancing Growth of Semipolar (Al,Ga,B)N Films via MOCVD

III-N Based Material Structures and Circuit Modules Based on Strain Management